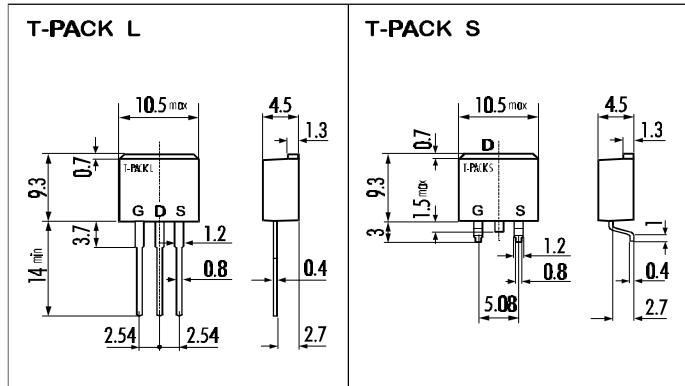


**> Features**

- High Speed Switching
- Low On-Resistance
- No Secondary Breakdown
- Low Driving Power
- High Voltage
- $V_{GS} = \pm 30V$  Guarantee
- Avalanche Proof

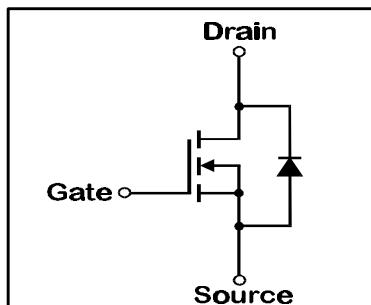
**> Applications**

- Switching Regulators
- UPS
- DC-DC converters
- General Purpose Power Amplifier

**> Outline Drawing**

**> Maximum Ratings and Characteristics**

- Absolute Maximum Ratings ( $T_C=25^\circ C$ ), unless otherwise specified

Item	Symbol	Rating	Unit
Drain-Source-Voltage	$V_{DS}$	250	V
Drain-Gate-Voltage ( $R_{GS}=20\text{ k}\Omega$ )	$V_{DGR}$	250	V
Continuous Drain Current	$I_D$	18	A
Pulsed Drain Current	$I_{D(\text{puls})}$	72	A
Gate-Source-Voltage	$V_{GS}$	$\pm 30$	V
Max. Power Dissipation	$P_D$	80	W
Operating and Storage Temperature Range	$T_{ch}$	150	$^\circ C$
	$T_{sta}$	-55 ~ +150	$^\circ C$

**> Equivalent Circuit**


- Electrical Characteristics ( $T_C=25^\circ C$ ), unless otherwise specified

Item	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown-Voltage	$V_{(BR)DSS}$	$I_D=1\text{ mA}$ $V_{GS}=0\text{ V}$	250			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$I_D=1\text{ mA}$ $V_{DS}=V_{GS}$	2,5	3,0	3,5	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=250\text{ V}$ $T_{ch}=25^\circ C$		10	500	$\mu A$
		$V_{GS}=0\text{ V}$ $T_{ch}=125^\circ C$		0,2	1,0	mA
Gate Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 30\text{ V}$ $V_{DS}=0\text{ V}$		10	100	nA
Drain Source On-State Resistance	$R_{DS(on)}$	$I_D=9\text{ A}$ $V_{GS}=10\text{ V}$		0,13	0,18	$\Omega$
Forward Transconductance	$g_{fs}$	$I_D=9\text{ A}$ $V_{DS}=25\text{ V}$	7	14		S
Input Capacitance	$C_{iss}$	$V_{DS}=25\text{ V}$		1750	2650	pF
Output Capacitance	$C_{oss}$	$V_{GS}=0\text{ V}$		290	440	pF
Reverse Transfer Capacitance	$C_{rss}$	$f=1\text{ MHz}$		65	100	pF
Turn-On-Time $t_{on}$ ( $t_{on}=t_{d(on)}+t_r$ )	$t_{d(on)}$	$V_{CC}=150\text{ V}$		30	45	ns
	$t_r$	$I_D=18\text{ A}$		50	75	ns
Turn-Off-Time $t_{off}$ ( $t_{off}=t_{d(off)}+t_f$ )	$t_{d(off)}$	$V_{GS}=10\text{ V}$		80	120	ns
	$t_f$	$R_{GS}=10\text{ }\Omega$		70	110	ns
Avalanche Capability	$I_{AV}$	$L=100\mu\text{H}$ $T_{ch}=25^\circ C$	18			A
Continuous Reverse Drain Current	$I_{DR}$	$T_C=25^\circ C$			18	A
Pulsed Reverse Drain Current	$I_{DRM}$	$T_C=25^\circ C$			72	A
Diode Forward On-Voltage	$V_{SD}$	$I_F=2xI_{DR}$ $V_{GS}=0\text{ V}$ $T_{ch}=25^\circ C$		1,0	1,5	V
Reverse Recovery Time	$t_{rr}$	$I_F=I_{DR}$ $V_{GS}=0\text{ V}$		150		ns
Reverse Recovery Charge	$Q_{rr}$	$-dI_F/dt=100\text{ A}/\mu\text{s}$ $T_{ch}=25^\circ C$		1		$\mu\text{C}$

- Thermal Characteristics

Item	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Thermal Resistance	$R_{th(ch-a)}$	channel to air			125	$^\circ C/W$
	$R_{th(ch-c)}$	channel to case			1,56	$^\circ C/W$

N-channel MOS-FET

250V 0,18Ω 18A 80W

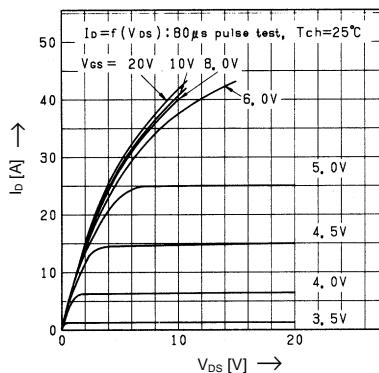
# 2SK2254-01L,S

## FAP-IIA Series

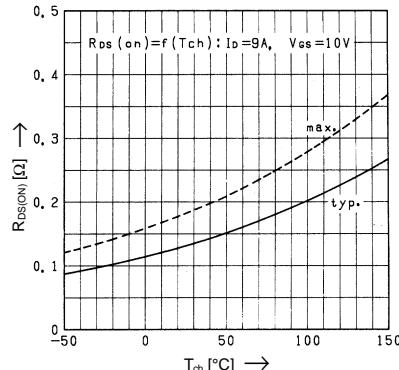
**FUJI**  
**ELECTRIC**

### > Characteristics

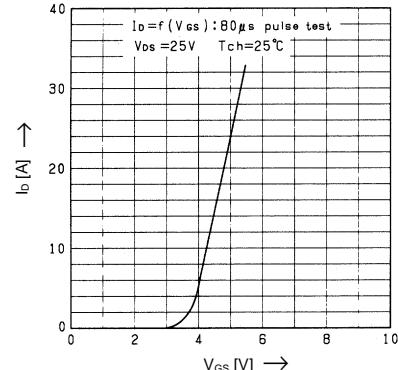
Typical Output Characteristics



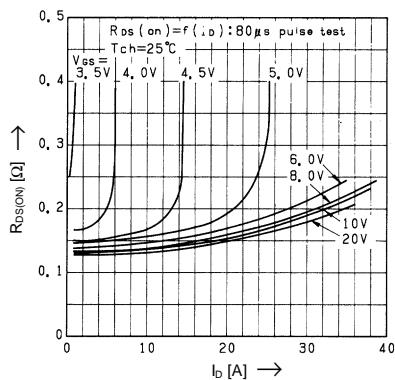
Drain-Source-On-State Resistance vs.  $T_{ch}$



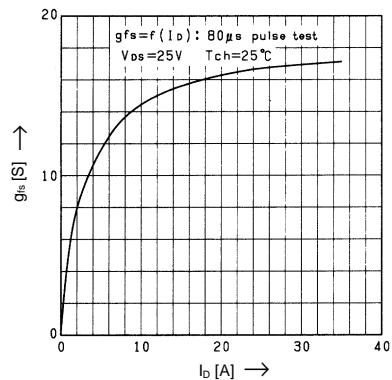
Typical Transfer Characteristics



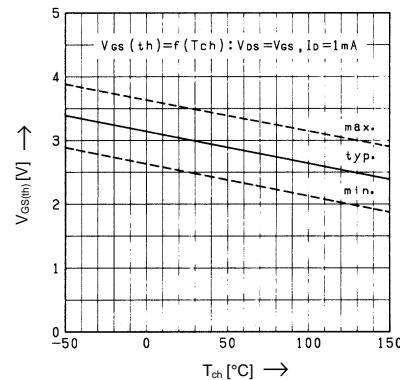
Typical Drain-Source-On-State-Resistance vs.  $I_D$



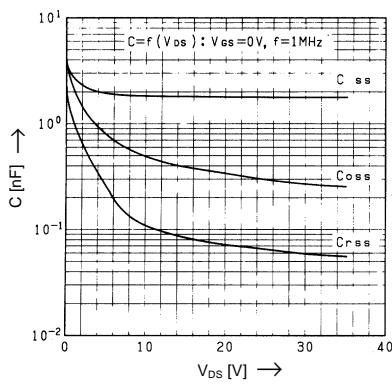
Typical Forward Transconductance vs.  $I_D$



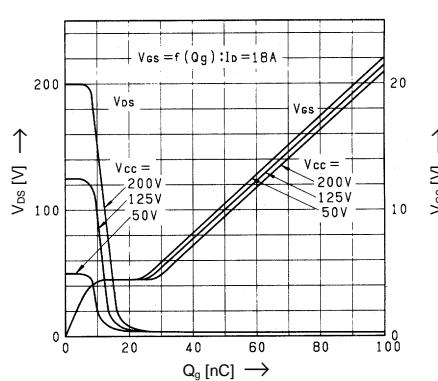
Gate Threshold Voltage vs.  $T_{ch}$



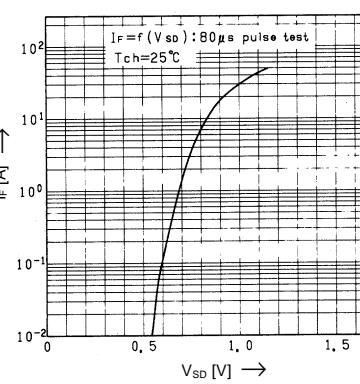
Typical Capacitance vs.  $V_{DS}$



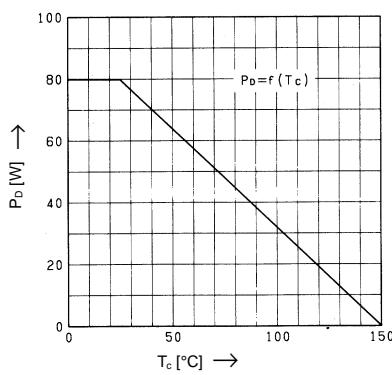
Typical Input Charge



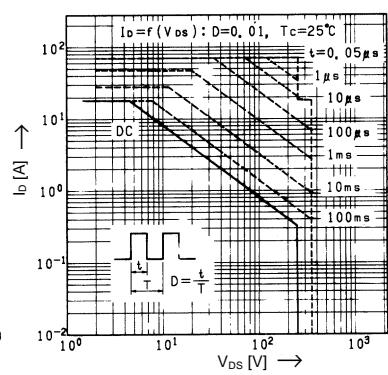
Forward Characteristics of Reverse Diode



Allowable Power Dissipation vs.  $T_c$



Safe operation area



Transient Thermal impedance

